Variant: 001
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TIDA-01165 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-01165	Any	Printed Circuit Board	
2	C1, C2	2	3.3uF	C1005X5R1A335K050BC	TDK	CAP, CERM, 3.3 µF, 10 V, +/- 10%, X5R, 0402	0402
3	C3	1	10uF	GRM155R61A106ME11	MuRata	CAP, CERM, 10 µF, 10 V, +/- 20%, X5R, 0402	0402
4	C4	1	0.1uF	C1005X5R1A104K	TDK	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	0402
5	D1, D2, D3, D4, D5, D6, D7, D8, D9, D10, D11, D12, D13, D14, D15, D16, D17, D18, D19, D20, D21, D22, D23, D24	24	Infrared	TSHF5410	Vishay-Semiconductor	LED, Infrared, TH	D5.8mm
6	FID4, FID5, FID6	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
7	J1, J2	2		53398-0271	Molex	Plug, SMT, Vertical, 1.25mm, 1x2	0533980271
8	Q2	1	12V	CSD13381F4	Texas Instruments	MOSFET, N-CH, 12 V, 2.1 A, PICOSTAR-3	YJC0003A
9	R3, R4	2	47k	CRCW040247K0JNED	Vishay-Dale	RES, 47 k, 5%, 0.063 W, 0402	0402
10	R5, R6	2	91k	CRCW040291K0JNED	Vishay-Dale	RES, 91 k, 5%, 0.063 W, 0402	0402
11	R7, R8, R9, R10, R18	5	110k	CRCW0402110KJNED	Vishay-Dale	RES, 110 k, 5%, 0.063 W, 0402	0402
12	R11, R12, R13, R14, R15, R16	6	18	CRCW201018R0JNEF	Vishay-Dale	RES, 18, 5%, 0.75 W, AEC-Q200 Grade 0, 2010	2010
13	R17, R19	2	150k	CRCW0402150KJNED	Vishay-Dale	RES, 150 k, 5%, 0.063 W, 0402	0402
14	U1	1		TLV3202AIDGK	Texas Instruments	40-ns, microPOWER, Push-Pull Output Comparators, DGK0008A	DGK0008A
15	U2	1		DRV8837CDSG	Texas Instruments	1-A Low-Voltage H-Bridge Driver, DSG0008A	DSG0008A
16	U3	1		SN74LVC1G32DCKR	Texas Instruments	SINGLE 2-INPUT POSITIVE-OR GATE, DCK0005A	DCK0005A
17	U4	1		OPL821	TT Electronics/IRC	Photologic Hermetic Sensor, TO-18	TO-18
18	U5	1	40V	SD103ASDM-7-F	Diodes Inc.	Diode, Schottky, 40 V, 0.35 A, SOT-26	SOT-26
19	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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